



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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PRINTED CIRCUIT BOARDS

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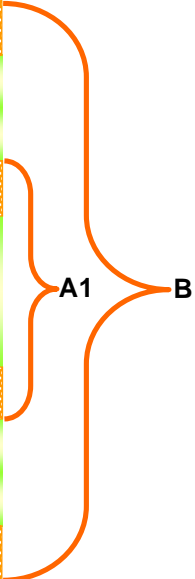
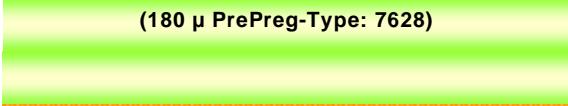


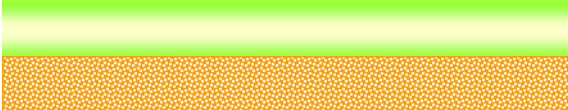
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 143 FR4 70 L36.105 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_143_FR4_700_L36.105_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	70 μ	Copper	 (180 μ PrePreg-Type: 7628)	
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	105 μ	Copper		
	360 μ	L-FR4		
Layer-3	105 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	70 μ	Copper		

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